



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **F0007-01** DATE: 08/04/00
Product Affected: FIFO Dual Die Products in PA 56 Package
(list of devices attached)
Manufacturing Location Affected: ALL
Date Effective: 09/04/00

MEANS OF DISTINGUISHING CHANGED DEVICES:

- ☐ Product Mark
☐ Back Mark Warning label on dry-pack
☐ Date Code
☒ Other

Contact: Dasharath Patel
Title: Quality Assurance Manager
Phone #: (408) 330-1488
Fax #: (408) 330-1450
E-mail: dasharath.patel@idt.com

Attachment: ☒ Yes ☐ No

Samples: Available upon request.

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
☐ Wafer Fabrication Process Packaging - introduction of dry-pack requirement, due to change in moisture classification from level I to level III (reclassification performed in accordance with J-STD-020A, which requires usage of a higher reflow temperature of 240C). Level III was determined to be more appropriate for customer shipment.
☐ Assembly Process
☐ Equipment
☐ Material
☐ Testing
☐ Manufacturing Site Please see attachment for details of products affected.
☐ Data Sheet
☒ Other

RELIABILITY/QUALIFICATION SUMMARY:

Available upon request.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____

☐ **Approval for shipments prior to effective date.**

Name/Date: _____

E-Mail Address: _____

Title: _____

Phone# /Fax# : _____

CUSTOMER COMMENTS:

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____

DATE: _____



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ATTACHMENT - PCN #: F0007-01

PCN Summary

PCN Type: Packaging/Label/Device Marking Change

Commodity FIFO Dual Die in PA 56 Package Type

Forecast or Execute Execute

Planned or Unplanned Unplanned

Data Sheet Change N/A

Detail of Change Moisture classification will be revised from Level I to Level III (as specified by J-STD-020A), for the following dual die devices in the PA 56 package :

7280, 7281, 7282, 7283, 7284, 7285
72V81, 72V82, 72V83, 72V84, 72V85

This reclassification was performed using the new reflow temperature of 240C, specified by J-STD-020A, and will be applicable to all speed grades of these products.

Conversion schedule (Estimated)

Sample Availability

Immediate

Production Shipments

9/4/00



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